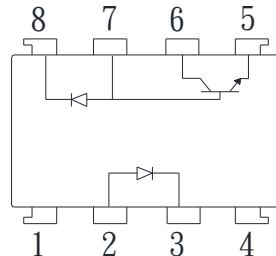


● Description

The KPC6N135 series consist of a LED optically coupled to an OPIC chip. It is a high-speed digital output type photocoupler designed specifically for low circuit current. And it is packaged in a 8 pin DIP package and available in wide-lead spacing and SMD option.

● Schematic



- | | |
|------------|-------------------|
| 1. N.C. | 5. GND |
| 2. Anode | 6. Vo |
| 3. Cathode | 7. V _B |
| 4. N.C. | 8. Vcc |

● Features

1. Pb free and RoHS compliant
2. High speed response t_{PHL}, t_{PLH} (Max. 1.5us at $R_L=4.1K\Omega$)
3. High common mode rejection voltage (CM_H : TYP. 1KV/us)
4. Standard dual-in-line package
5. MSL class 1
6. Agency Approvals:
 - UL Approved (No. E169586): UL1577
 - c-UL Approved (No. E169586)
 - FIMKO Approved: EN60065, EN60950

● Applications

- Computers, measuring instruments, control equipment
- High speed line receivers, high speed logic
- Telephone sets
- Signal transmission between circuits of different potentials and impedances



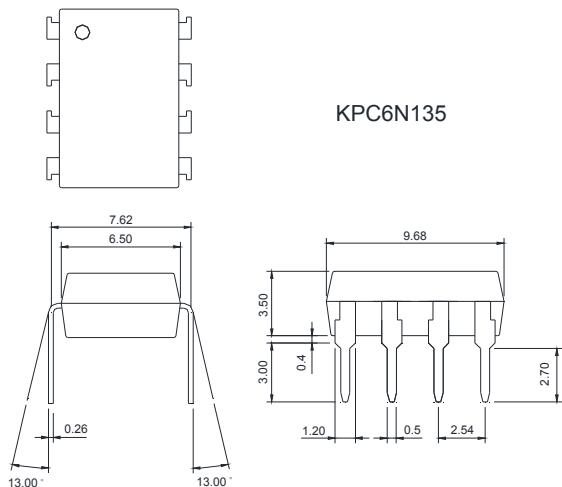
KPC6N135 Series

8PIN HIGH-SPEED OUTPUT PHOTOCOUPLER

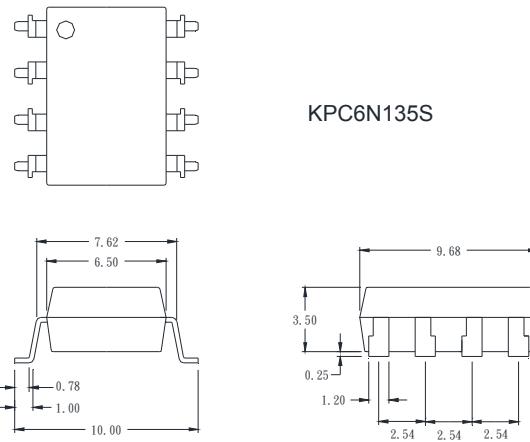
● Outside Dimension

Unit : mm

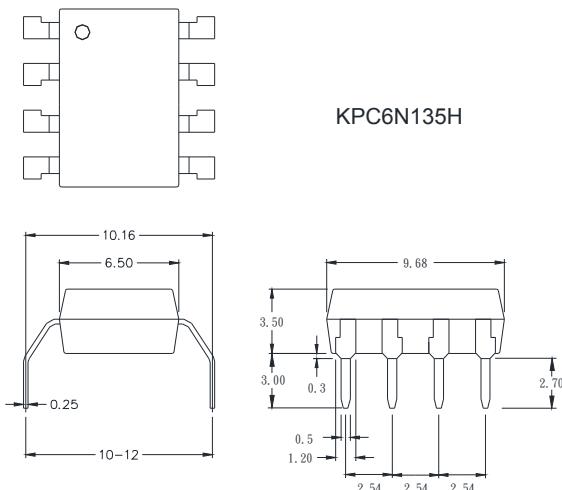
1.Dual-in-line type



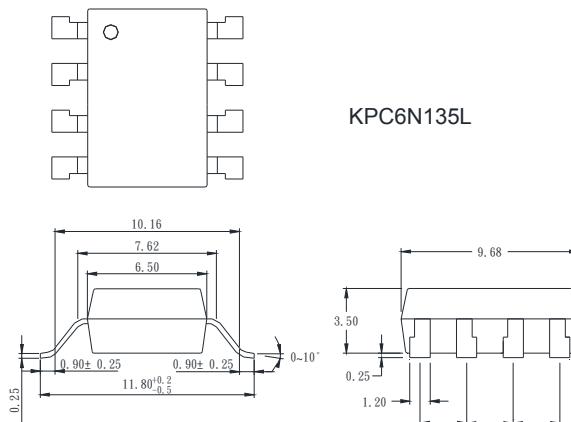
2.Surface mount type



3.Long creepage distance type

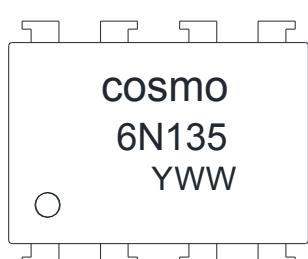


4.Long creepage distance
for surface mount type



TOLERANCE: ±0.2mm

● Device Marking



Notes:

c
osmo
6N135
YWW

Y: Year code / WW: Week code



KPC6N135 Series

8PIN HIGH-SPEED OUTPUT
PHOTOCOUPLER

Absolute Maximum Ratings

(Ta = 25°C)

Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	25 mA
	*1 Peak forward current	I _F	50 mA
	*2 Peak transient forward current	I _{FM}	1 A
	Reverse voltage	V _R	5 V
Output	Power dissipation	P	45 mW
	Supply voltage	V _{CC}	-0.5 to 15 V
	Output voltage	V _O	-0.5 to 15 V
	Emitter-base reverse with stand voltage (Pin5 to 7)	V _{EBO}	5 V
	Average output current	I _O	8 mA
	Peak output current	I _{OP}	16 mA
	Base current (Pin7)	I _B	5 mA
	Power dissipation	P _O	100 mW
	*3 Isolation voltage 1 minute	V _{iso}	5000 Vrms
	Operating temperature	T _{opr}	-55 to +100 °C
	Storage temperature	T _{stg}	-55 to +125 °C
	*4 Soldering temperature 10 seconds	T _{sol}	260 °C

*1 50% duty cycle, Pulse width : 1mS

Decreases at the rate of 1.6mA/°C if the external temperature is 70°C or more.

*2 Pulse width≤1uS, 300pulse/sec

*3 40 to 60% RH, AC for 1 minute

*4 For 10 seconds

Electrical Characteristics

(Ta = 25°C)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
*5 Current transfer ratio	CTR(1)	Ta=25°C, I _F =16mA V _O =0.4V, V _{CC} =4.5V	7	40	-	%
	CTR(2)	I _F =16mA V _O =0.5V, V _{CC} =4.5V	5	43	-	%
Logic (0) output voltage	V _{OL}	*6 V _{CC} =4.5V, I _F =16mA	-	0.1	0.4	V
Logic (1) output current	I _{OH(1)}	Ta=25°C, I _F =0 V _O =V _{CC} =5.5V	-	3.0	500	nA
	I _{OH(2)}	Ta=25°C, I _F =0 V _O =V _{CC} =15V	-	0.01	1.0	uA
	I _{OH(3)}	V _{CC} =V _O =15V, I _F =0	-	-	50	uA
Logic (0) supply current	I _{CCL}	I _F =16mA V _O =open, V _{CC} =15V	-	200	-	uA
Logic (1) supply current	I _{CCH(1)}	Ta=25°C, I _O =0 V _F =open, V _{CC} =15V	-	0.02	1.0	uA
	I _{CCH(2)}	I _O =0 V _O =open, V _{CC} =15V	-	-	2.0	uA
Input forward voltage	V _F	Ta=25°C, I _F =16mA	-	1.7	1.95	V
Input forward voltage temperature coefficient	△V _F /△Ta	I _F =16mA	-	-1.9	-	mV/°C
Input reverse voltage	BV _R	Ta=25°C, I _R =10uA	5.0	-	-	V
Input capacitance	C _{IN}	V _F =0, f=1MHz	-	60	-	pF
*7 Leak current (input-output)	I _{I-O}	Ta=25°C, 45%RH V _{I-O} =3KVDC, t=5s	-	-	1.0	uA
*7 Isolation resistance (input-output)	R _{I-O}	V _{I-O} =500VDC	-	10 ¹²	-	Ω
*7 Capacitance (input-output)	C _{I-O}	f=1MHz	-	0.6	-	pF
Transistor current amplification factor	h _{FE}	V _O =5V, I _O =3mA	-	70	-	

*5 Current transfer ratio is the ratio of input current and output current expressed in %

*6 I_O=1.1mA

*7 Measured as 2-pin element (Short 1, 2, 3, 4 and 5, 6, 7, 8)

● Switching Characteristics
 $(Ta=25^\circ\text{C}, V_{CC}=5\text{V}, I_F=16\text{mA} \text{ Ta} = 25^\circ\text{C})$

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
*8 Propagation delay time *9 Output (1) → (0)	t_{PHL}	$R_L=4.1\text{K}\Omega$	-	0.3	1.5	μs
*8 Propagation delay time *9 Output (0) → (1)	t_{PLH}	$R_L=4.1\text{K}\Omega$	-	0.4	1.5	μs
*10 Instantaneous common mode rejection voltage *11 "Output (1)"	CM_H	$I_F=0, V_{CM}=10\text{V}_{P-P}$	-	1000	-	$\text{V}/\mu\text{s}$
*10 Instantaneous common mode rejection voltage *11 "Output (0)"	CM_L	$I_F=16\text{mA}, V_{CM}=10\text{V}_{P-P}$	-	-1000	-	$\text{V}/\mu\text{s}$
*12 Bandwidth	BW	$R_L=100\Omega$	-	2.0	-	MHz

*8 $R_L=4.1\text{K}\Omega$ is equivalent to one LSTTL and 6.1KΩ pull-up resistor.

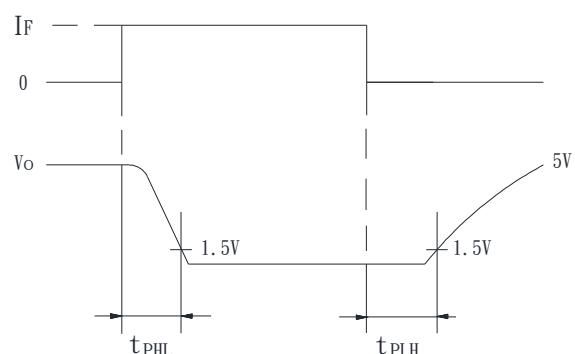
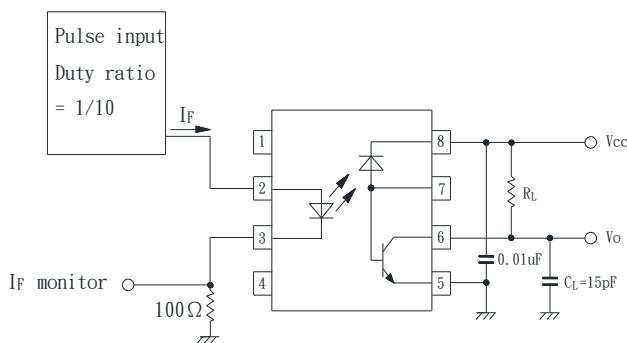
*10 Instantaneous common mode rejection voltage "output (1)" represents a common mode voltage variation that can hold the output above (1) level ($V_o > 2.0\text{V}$)

Instantaneous common mode rejection voltage "output (0)" represents

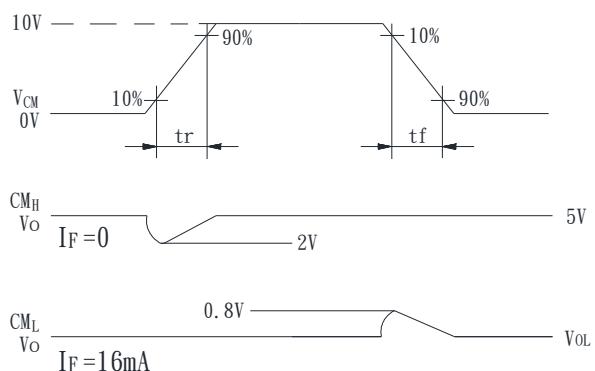
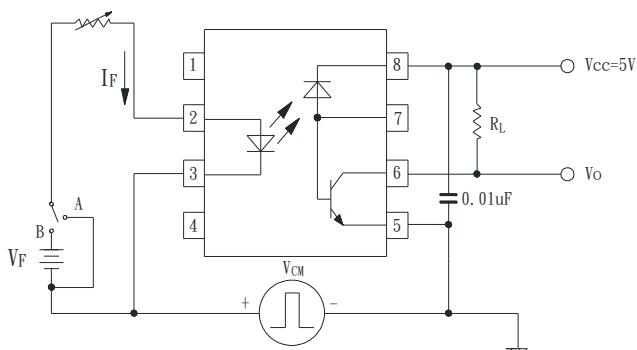
a common mode voltage variation that can hold the output above (0) level ($V_o < 0.8\text{V}$)

*12 Bandwidth represents a point where AC input goes down by 3dB.

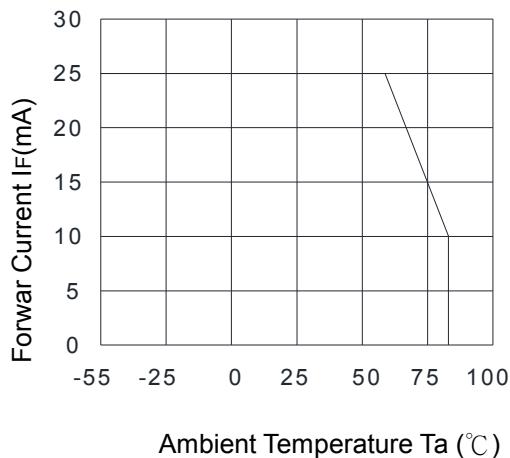
*9 Test Circuit Propagation Delay Time



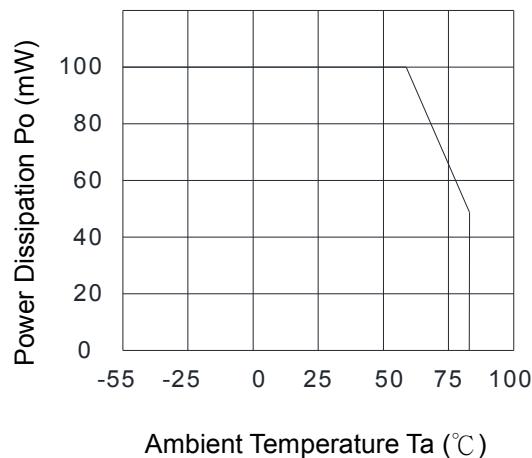
*11 Test Circuit for Instantaneous Common Mode Rejection Voltage



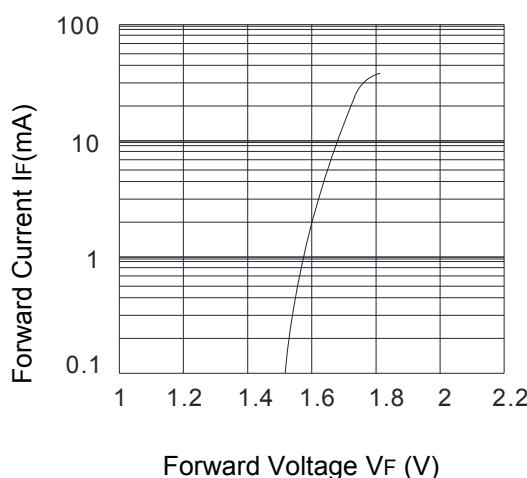
**Fig.1 Forward Current
vs. Ambient Temperature**



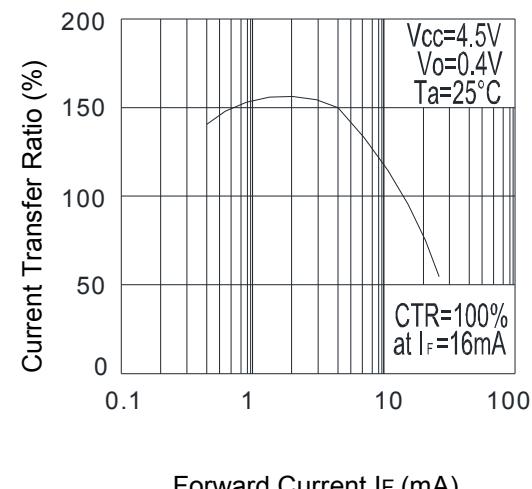
**Fig.2 Power Dissipation
vs. Ambient Temperature**



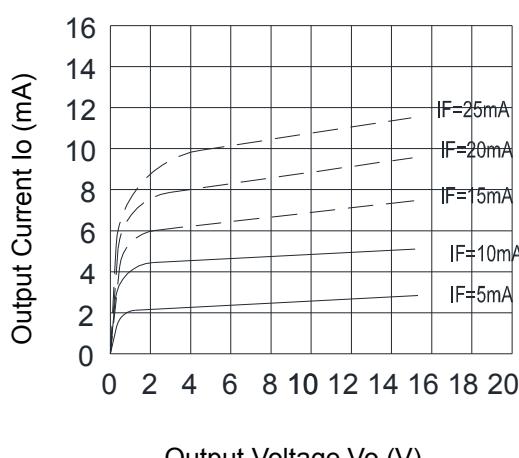
**Fig.3 Forward Current
vs. Forward Voltage**



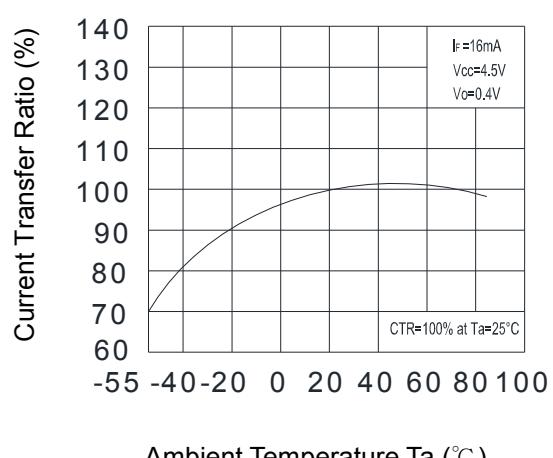
**Fig.4 Current Transfer Ratio
vs. Forward Current**



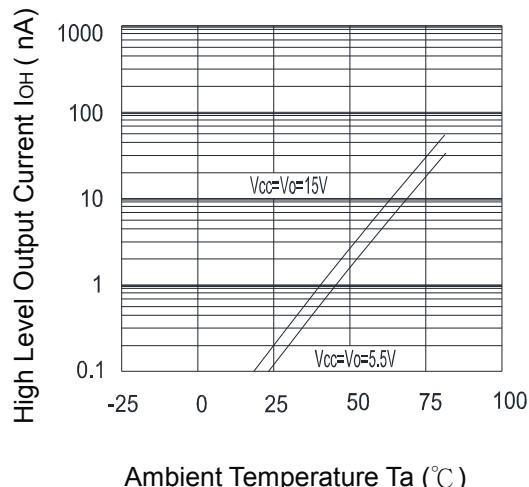
**Fig.5 Output Current
vs. Output Voltage**



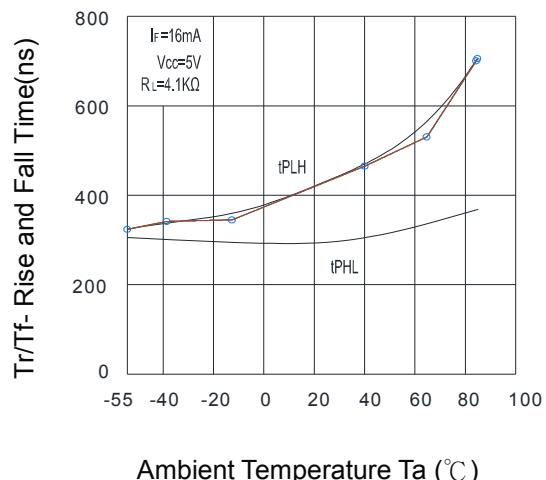
**Fig.6 Current Transfer Ratio
vs. Ambient Temperature**



**Fig.7 High Level Output Current
vs. Ambient Temperature**



**Fig.8 Propagation Delay Time
vs. Ambient Temperature**

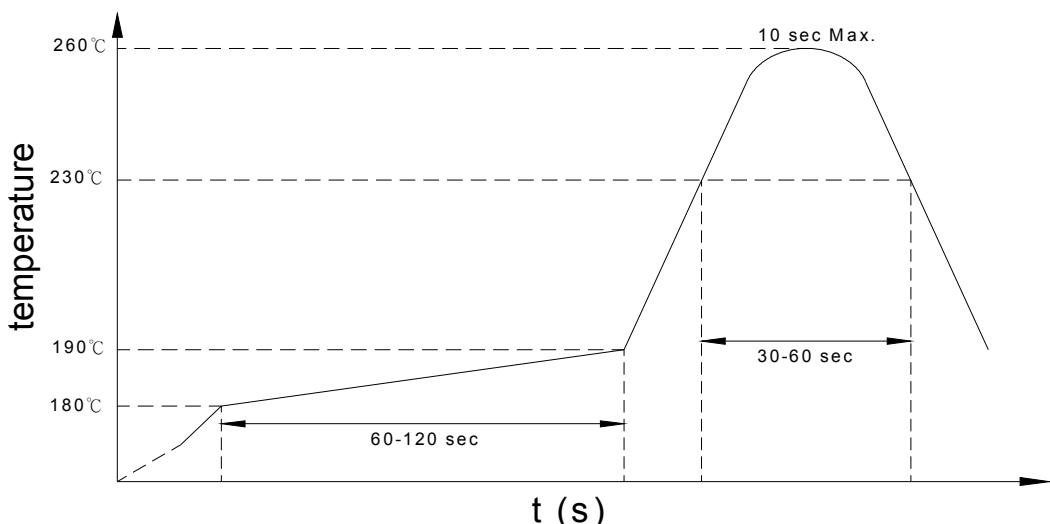


● Recommended Soldering Conditions

(a) Infrared reflow soldering :

- Peak reflow soldering : 260°C or below (package surface temperature)
- Time of peak reflow temperature : 10 sec
- Time of temperature higher than 230°C : 30-60 sec
- Time to preheat temperature from 180~190°C : 60-120 sec
- Time(s) of reflow : Two
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(b) Wave soldering :

- Temperature : 260°C or below (molten solder temperature)
- Time : 10 seconds or less
- Preheating conditions : 120°C or below (package surface temperature)
- Time(s) of reflow : One
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(c) Cautions :

- Fluxes : Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Avoid shorting between portion of frame and leads.

- Numbering System

KPC6N135 X (Y)

Notes:

KPC6N135 = Part No.

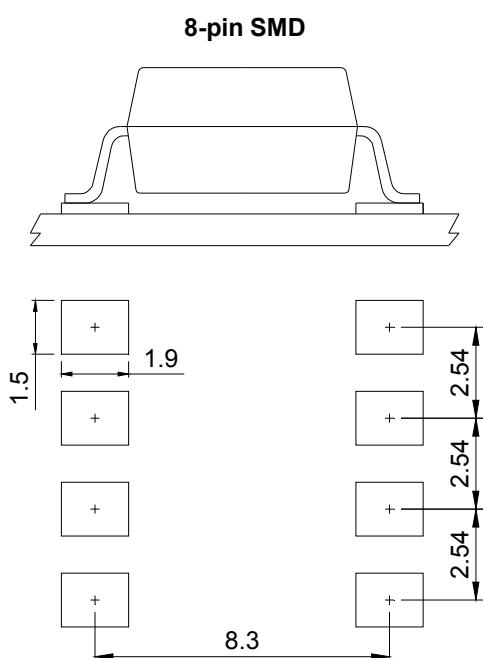
X = Lead form option (blank、S、H、L)

Y = Tape and reel option (TL、TR、TLD、TRU)

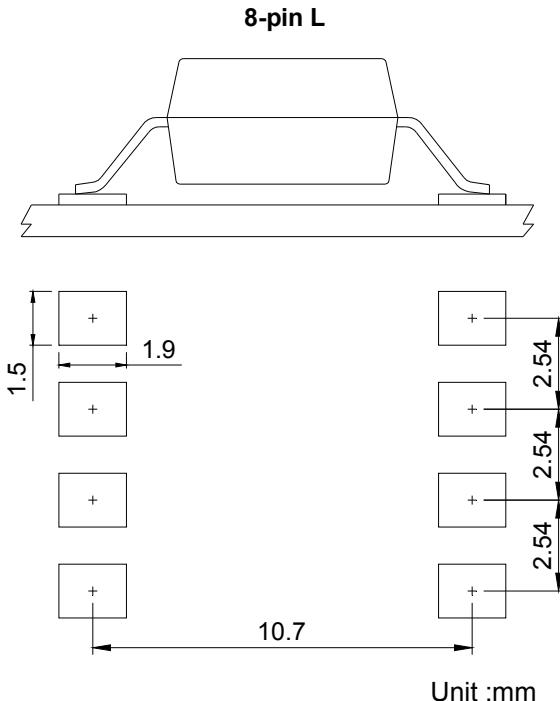
Option	Description	Packing quantity
S (TL)	surface mount type package + TL tape & reel option	1000 units per reel
S (TR)	surface mount type package + TR tape & reel option	1000 units per reel
L (TLD)	long creepage distance for surface mount type package + TLD tape & reel option	800 units per reel
L (TRU)	long creepage distance for surface mount type package + TRU tape & reel option	800 units per reel

- Recommended Pad Layout for Surface Mount Lead Form

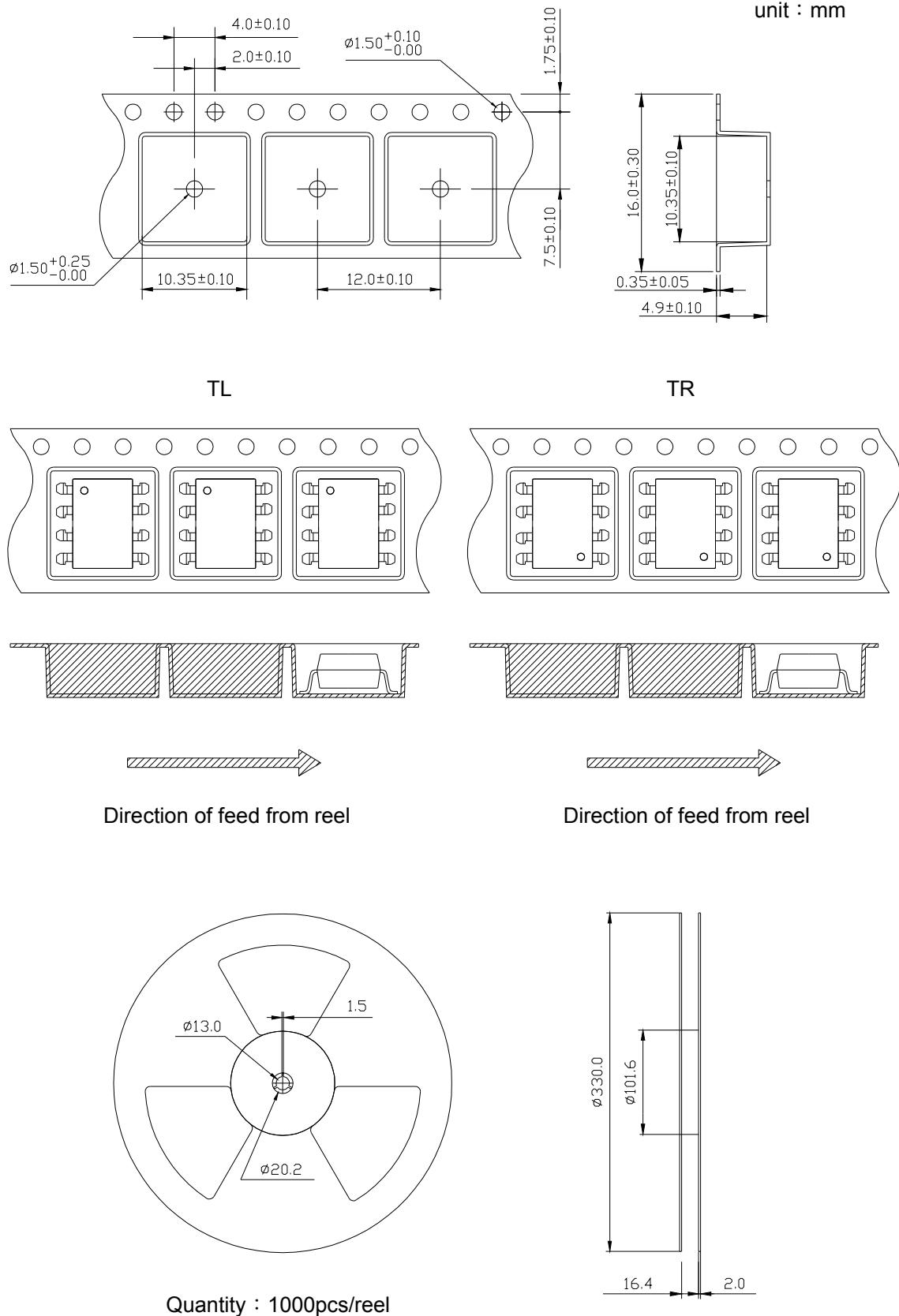
1.Surface mount type



**2.Long creepage distance
for surface mount type**



- 8-pin SMD Carrier Tape & Reel

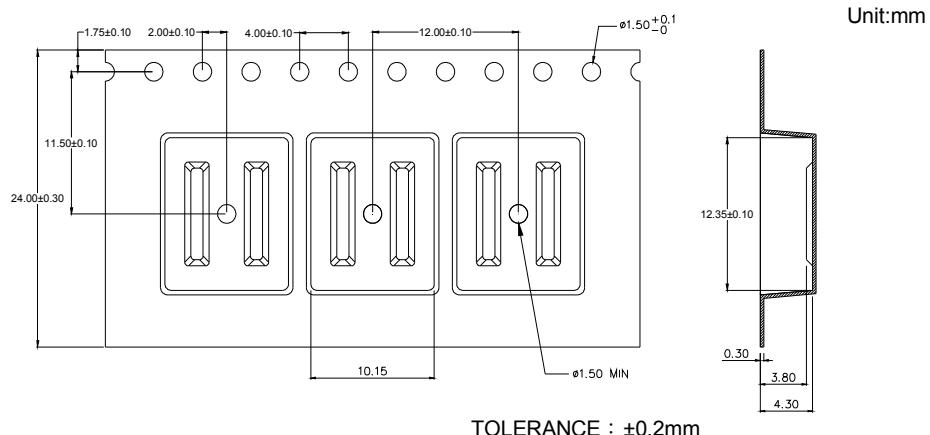




KPC6N135 Series

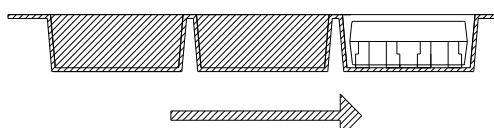
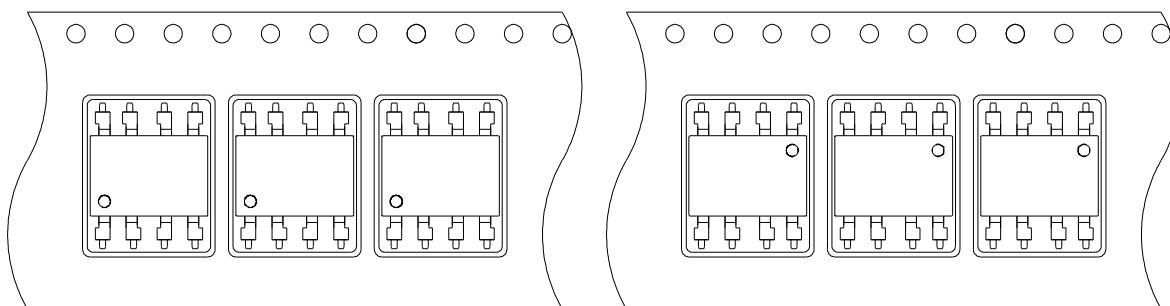
8PIN HIGH-SPEED OUTPUT PHOTOCOUPLER

● 8-pin L Carrier Tape & Reel

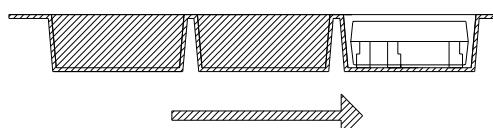


TLD

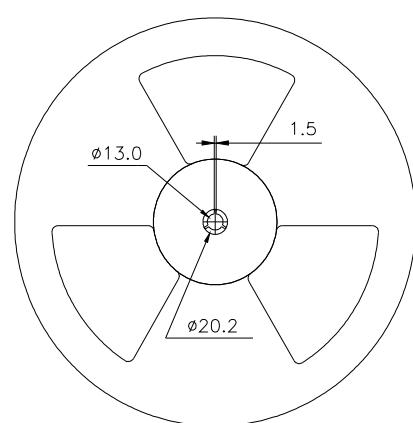
TRU



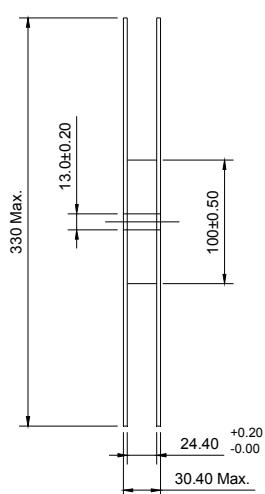
Direction of feed from reel



Direction of feed from reel



Quantity : 800pcs/reel





KPC6N135 Series

8PIN HIGH-SPEED OUTPUT PHOTOCOUPLER

● Application Notice

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